

ABSTRACT

The present invention addresses the problem of providing: a phenol mixture optimal as a raw material for the production of an epoxy resin that can realize a high heat resistance as required in recent years; and an epoxy resin, an epoxy resin composition, a cured product, and an electrical/electronic component, in which the phenol mixture is used. The problem is solved by: a phenol mixture containing 3,3',5,5'-tetramethyl-4,4'-biphenol as a main component, which phenol mixture further contains more than 0.3% by weight but less than 10.0% by weight of a polyphenylene ether, and 1.3% by weight to 4.0% by weight of tetramethyldiphenoquinone; and an epoxy resin, an epoxy resin composition, a cured product, and an electrical/electronic component, in which the phenol mixture is used.

(No Suitable Fig.)